

AMENDMENTS TO THE CLAIMS

The following is a complete listing of the claims, which replaces all previous versions and listings of the claims.

1-14. (cancelled)

15. (currently amended) A system for connecting an integrated circuit device, comprising:

a circuit board, comprising:

a first set of traces ~~at least partially~~ free of termination components; and
a first interface coupled to the first set of traces; and

an interstitial circuit board, comprising:

a second interface coupled to the first interface;
a second set of traces coupled to the second interface and having a plurality
of termination components; and
a third interface coupled to the second set of traces, wherein the third
interface is adapted to couple with the integrated circuit device.

16. (original) The system of claim 15, comprising the integrated circuit device, which comprises a processor.

17. (original) The system of claim 15, comprising the integrated circuit device, which comprises a memory controller.

18. (original) The system of claim 15, comprising the integrated circuit device, which comprises an input/output controller.

19. (original) The system of claim 15, comprising the integrated circuit device, which comprises an application specific integrated circuit.

20. (original) The system of claim 15, wherein the system comprises a computer system.

21. (original) The system of claim 15, wherein the circuit board comprises a computer motherboard.

22. (original) The system of claim 15, wherein the plurality of termination components are disposed in multiple levels of the interstitial circuit board.

23. (original) The system of claim 22, wherein the multiple levels comprise power and ground planes.

24. (original) The system of claim 15, wherein the interstitial circuit board has a substantially smaller footprint than the circuit board.

25. (original) The system of claim 15, wherein the plurality of termination components comprise a resistor.

26. (currently amended) A system, comprising:
a first circuit board comprising first traces free of termination components and
leading to a first electrical interface;
a second circuit board comprising a second electrical interface mounted to the first
electrical interface and second traces extending from the second ~~electrical~~
electrical interface to a third electrical interface for an integrated circuit
device, wherein the second traces comprise means for reducing signal
degradation.

27-33. (cancelled)

34. (currently amended) A system ~~for connecting an integrated circuit device to a circuit board~~, comprising:

an integrated circuit device having a first interface; ~~and~~

an interstitial circuit board, comprising:

a second interface coupled to the first interface;

a set of traces coupled to the second interface and having a plurality of termination components; and

a third interface coupled to the set of traces, ~~wherein the third interface is adapted to couple with the circuit board; and~~

a circuit board, comprising:

a fourth interface coupled to the third interface; and

a plurality of traces coupled to the fourth interface and free of termination components.

35. (cancelled)

36. (original) The system of claim 34, wherein the integrated circuit device comprises a processor.

37. (original) The system of claim 34, wherein the plurality of termination components are disposed in multiple layers of the interstitial circuit board.

38. (original) The system of claim 37, wherein the multiple layers comprise power and ground planes.

39. (original) The system of claim 34, wherein the plurality of termination components are selected from a group consisting of a resistor, a capacitor, an inductor, and a diode.